Abstract of the Disclosure

Provided is a multi-chip semiconductor package incorporating stacked semiconductor package structures with each package structure including a substrate, a semiconductor chip mounted on the substrate, an enclosure body formed across the entire surface of the substrate where the semiconductor chip is mounted, a plurality of conductive studs extending through the enclosure body outside the periphery of the semiconductor chip and one or more conductive members provided below the substrate and in contact with the conductive studs. During assembly of the multi-chip semiconductor package, the conductive member of an upper semiconductor package structure provides electrical contact to corresponding conductive studs on a lower semiconductor package structure.